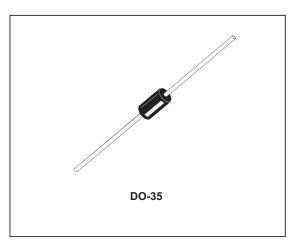


SMALL SIGNAL SCHOTTKY DIODE



DESCRIPTION

General purpose, metal to silicon diodes featuring very low turn-on voltage and fast switching.These devices have integrated protection against excessive voltage such as electrostatic discharges.

Symbol	Parameter		BAT47	BAT48	Unit
V _{RRM}	Repetitive Peak Reverse Voltage		20	40	V
١ _F	Forward Continuous Current*	T _a = 25°C	350		mA
I _{FRM}	Repetitive Peak Fordward Current*	$\begin{array}{l} t_p \leq 1s \\ \delta \leq 0.5 \end{array}$	1		A
I _{FSM}	Surge non Repetitive Forward Current*	t _p = 10ms	7.5		А
		t _p = 1s	1.5		
P _{tot}	Power Dissipation*	T _a = 25°C	330		mW
T _{stg} Tj	Storage and Junction Temperature Range		- 65 to + 150 - 65 to + 125		°C ℃
TL	Maximum Temperature for Soldering during 10s at 4mm from Case		230		°C

ABSOLUTE RATINGS (limiting values)

THERMAL RESISTANCE

S	ymbol	Test Conditions	Value	Unit
F	R _{th(j-l)}	Junction-ambient*	300	°C/W

* On infinite heatsink with 4mm lead length

ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Symbol	Т	est Conditions		Min.	Тур.	Max.	Unit
V _(BR)	I _R = 10μA		BAT47	20			V
	I _R = 25μA		BAT48	40			
V _F *	$T_j = 25^{\circ}C$ $I_F = 0.1mA$		All Types			0.25	V
	T _j = 25°C I _F = 1mA					0.3	
	T _j = 25°C I _F = 10mA					0.4	
	T _j = 25°C I _F = 30mA		BAT47			0.5	
	T _j = 25°C I _F = 150mA					0.8	
	T _j = 25°C I _F = 300mA					1	
	T _j = 25°C I _F = 50mA	-	BAT48			0.5	
	T _j = 25°C I _F = 200mA					0.75	
	T _j = 25°C I _F = 500mA					0.9	
I _R *	T _j = 25°C	V _R = 1.5V	All Types			1	μA
	T _j = 60°C					10	
	T _j = 25°C	V _R = 10V	BAT47			4	
	T _j = 60°C					20	-
	T _j = 25°C	V _R = 20V				10	
	T _j = 60°C					30	
	T _j = 25°C	V _R = 10V	BAT48			2	
	T _j = 60°C					15	
	T _j = 25°C	V _R = 20V				5	
	T _j = 60°C					25	
	T _j = 25°C	V _R = 40V				25	
	T _i = 60°C					50	

DYNAMIC CHARACTERISTICS

Symbol	Test Conditions			Тур.	Max.	Unit
С	$T_j = 25^{\circ}C$ $V_R = 0V$	f = 1MHz		20		pF
	T _j = 25°C V _R = 1V			12		

57

* Pulse test: $t_p \leq 300 \mu s ~~\delta < 2 \%$.

Fig. 1: Forward current versus forward voltage at different temperatures (typical values).

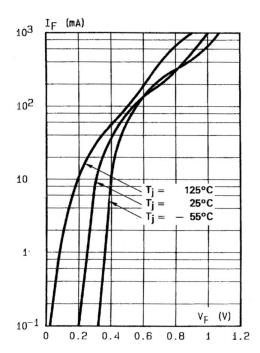


Fig. 3: Reverse current versus junction temperature.

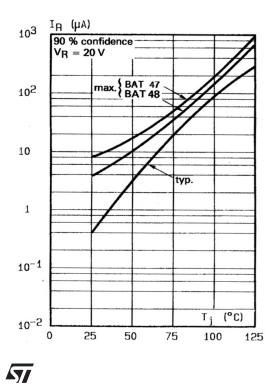


Fig. 2: Forward current versus forward voltage (typical values).

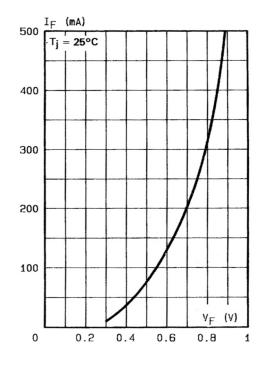
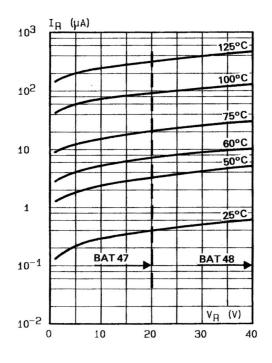


Fig. 4: Reverse current versus continuous reverse voltage (typical values).



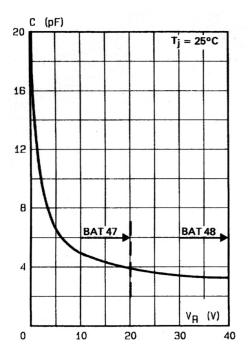
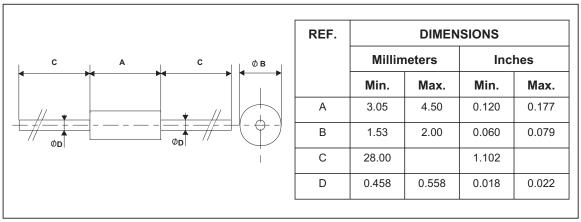


Fig. 5: Capacitance C versus reverse applied voltage $V_{\mbox{\tiny R}}$ (typical values).

PACKAGE MECHANICAL DATA

DO-35



Cooling method: by convection and conduction. Marking: clear, ring at cathode end. Weight: 0.015g

Information furnished is believed to be accurate and reliable. However, STMicroelectronics assumes no responsibility for the consequences of use of such information nor for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of STMicroelectronics. Specifications mentioned in this publication are subject to change without notice. This publication supersedes and replaces all information previously supplied.

STMicroelectronics products are not authorized for use as critical components in life support devices or systems without express written approval of STMicroelectronics.

The ST logo is a registered trademark of STMicroelectronics

© 2001 STMicroelectronics - Printed in Italy - All rights reserved.

STMicroelectronics GROUP OF COMPANIES

Australia - Brazil - China - Finland - France - Germany - Hong Kong - India - Italy - Japan - Malaysia Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - U.S.A.

http://www.st.com

